

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LMV611MF/NOPB	Active	Production	SOT-23 (DBV) 5	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AE9A
LMV611MF/NOPB.A	Active	Production	SOT-23 (DBV) 5	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AE9A
LMV611MFX/NOPB	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AE9A
LMV611MFX/NOPB.A	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AE9A
LMV611MG/NOPB	Active	Production	SC70 (DCK) 5	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AVA
LMV611MG/NOPB.A	Active	Production	SC70 (DCK) 5	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AVA
LMV611MGX/NOPB	Active	Production	SC70 (DCK) 5	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AVA
LMV611MGX/NOPB.A	Active	Production	SC70 (DCK) 5	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AVA
LMV612MA/NOPB	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV6 12MA
LMV612MA/NOPB.A	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV6 12MA
LMV612MAX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV6 12MA
LMV612MAX/NOPB.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV6 12MA
LMV612MM/NOPB	Active	Production	VSSOP (DGK) 8	1000 SMALL T&R	Yes	NIPDAUAG SN	Level-1-260C-UNLIM	-40 to 125	AD9A
LMV612MM/NOPB.A	Active	Production	VSSOP (DGK) 8	1000 SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AD9A
LMV612MMX/NOPB	Active	Production	VSSOP (DGK) 8	3500 LARGE T&R	Yes	NIPDAUAG SN	Level-1-260C-UNLIM	-40 to 125	AD9A
LMV612MMX/NOPB.A	Active	Production	VSSOP (DGK) 8	3500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	AD9A
LMV614MA/NOPB	Active	Production	SOIC (D) 14	55 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV614MA
LMV614MA/NOPB.A	Active	Production	SOIC (D) 14	55 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV614MA
LMV614MAX/NOPB	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV614MA
LMV614MAX/NOPB.A	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	LMV614MA
LMV614MT/NOPB	Active	Production	TSSOP (PW) 14	94 TUBE	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	LMV61 4MT
LMV614MT/NOPB.A	Active	Production	TSSOP (PW) 14	94 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LMV61 4MT
LMV614MTX/NOPB	Active	Production	TSSOP (PW) 14	2500 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	LMV61 4MT

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LMV614MTX/NOPB.A	Active	Production	TSSOP (PW) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LMV61 4MT

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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